

Expanding IBIS for Power Simulations

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Objective

Expand the IBIS simulation capabilities on power integrity, power consumption, and SI/PI co-simulations



General rules

- Use the existing IBIS keywords as much as possible
- Focus on the coverage more than modeling accuracy
- The DC and power losses
- The AC impedance, from buck/booster converter to loading
- The transient, from buck/booster converter to loading



Passive elements

Here are a list of all possible passive elements:

- Resistor: mostly for current sensing.
- Capacitor: mostly for noise decoupling. It is covered relatively well with RLC and s-parameter models.
- Inductor: critical for switching power suppliers:
- Transformer and/or coupled inductor: less popular
- Connector (maybe this already available in IBIS)

Solution available

Focus of current power standardization

Future power standard expansion



Active discrete elements

Here are a list of all possible active elements:

- Power Diode:
- Transistor: FET (voltage drive):
- Transistor: BJT (smaller power & high voltage) (current drive):
- Diode/transistor combination:

Solution available

Focus of current power standardization

Future power standard expansion



Integrated power solutions

Here are a list of all possible DC/DC converters:

- PMIC (Power Management IC) controller (not FET)
- DC/DC converter with integrated power stage
- LDO (Low Dropout Regulators)

Solution available

Focus of current power standardization

Future power standard expansion



Sinks/Loads

Examples:

- Core power supplies – Songping/Kinger/Chi-te
- I/O power supplies - AC/DC/Transient?

Solution available

Focus of current power standardization

Future power standard expansion

SPIM - Chip level Standard Power Integrity Model

.spim FILE

```

|-- File Header Section
-----
[IBIS Ver] 7.x
[Comment Chart] (ml)
[File name]
[File rev]
[Date]
[Source]
[Disclaimer]
[Copyright]

|-- [Begin Chip SPIM] component_name
-----
[Manufacturer]
[Description]

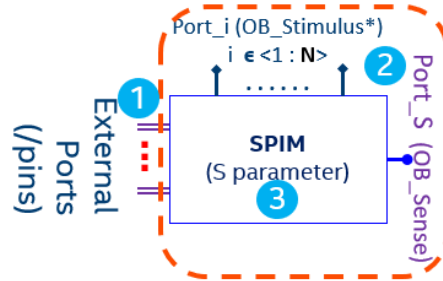
| [Begin SPIM] Power_signal_name (m)
-----

[SPIM Pin Groups] Power_signal_name Gnd_signal_name
| Pin_group_name Pin_name
-----
|-- [End SPIM Pin Groups]

[SPIM Port List]
| Port Terminal_p Terminal_n |Port_function(optional)
| # OB_Stimulus_#_p OB_Stimulus_#_n |OB_Stimulus_#
| # OB_Sense_#_p OB_Sense_#_n |OB_Sense_#
-----
|-- [End SPIM Port List]

```

Tree Structure of .spim FILE



```

[SPIM Touchstone File Name]
-----

[SPIM Stimulus]
|OB_Stimulus Weighting
-----
|-- [End SPIM Stimulus]

[SPIM Target]
[SPIM Observation Port]
|Frequency Z(typ) Z(min) Z(max)
-----
|-- [End SPIM Target]

[SPIM Rnetwork File Name]
-----

[SPIM Current]
|I(name) I(type) I(min) I(max)
-----
|-- [End SPIM Current]

[Voltage List]
|V(name) V(typ) V(min) V(max)
-----
|-- [End Voltage List]

| [End SPIM] Power_singal_name
| [End Chip SPIM] component_name

[End]

```



Input/output power interfaces

Examples:

- Wired USB-C interface
- Simple charging port
- Wireless charging



Battery pack

- To be determined



Conclusion

- Proposal to add new components into IBIS to implement the end-to-end power integrity simulations from die to regulator
- People who are interested are welcome to join the discussion and contribute their ideas